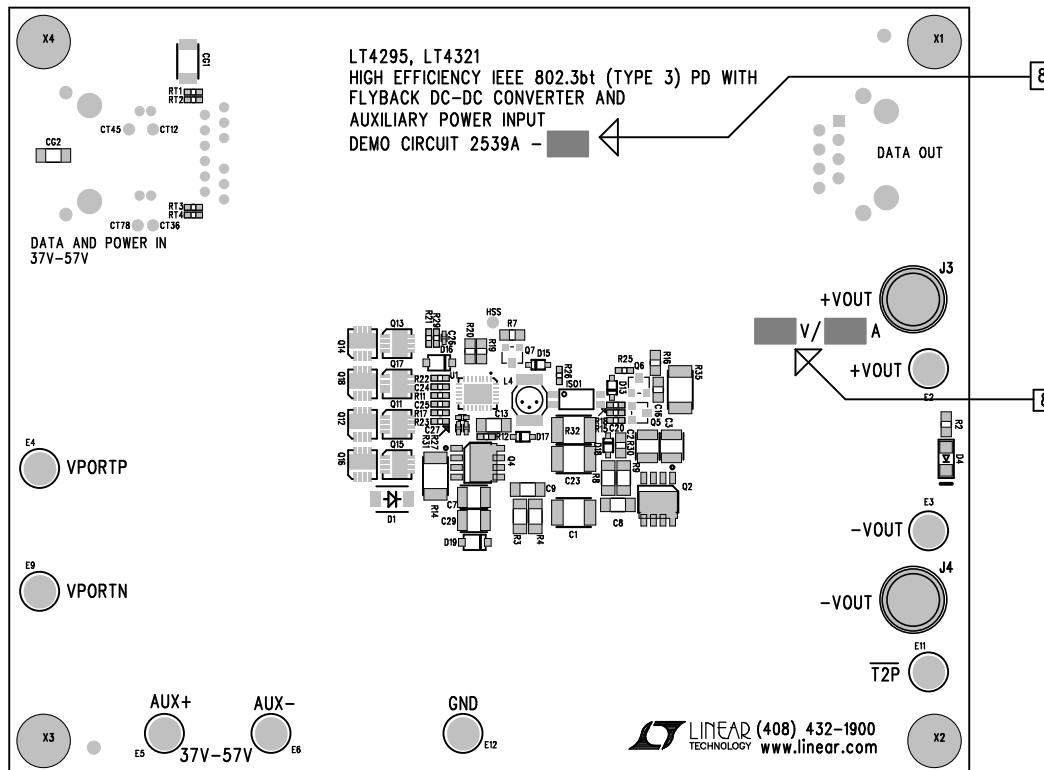


ASSEMBLY DRAWING TOP



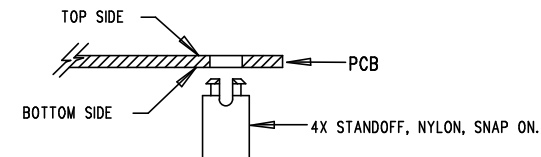
L1 - Top Layer

REVISION HISTORY

ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	PRODUCTION	KAUNG H.	8-18-16

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
5. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
6. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



7. INSTALL D4 AS SHOWN BELOW:



8. MARK EACH ASSEMBLY TYPE, OUTPUT VOLTAGE, AND CURRENT IN THE WHITE BLOCK AREAS WITH BLACK PERMANENT MARKER AS SHOWN IN TABLE BELOW:

ASSY TYPE	VOLTAGE	CURRENT
-A	12V	3.9A
-B		
-C		
-D		
-E		
-F		

APPROVALS

PCB DES.	KAUNG H.
APP ENG.	KAUNG H.



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TITLE: TOP ASSEMBLY DRAWING
IEEE 802.3bt (TYPE 3) PD WITH
FLYBACK DC-DC CONVERTER

SIZE	IC NO. LT4295IUF, LT4321IUF	REV.
N/A	DEMO CIRCUIT 2539A	2

SCALE = NONE

FILENAME: DC2539A-1.PCB

SHT 1 OF 2